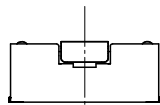
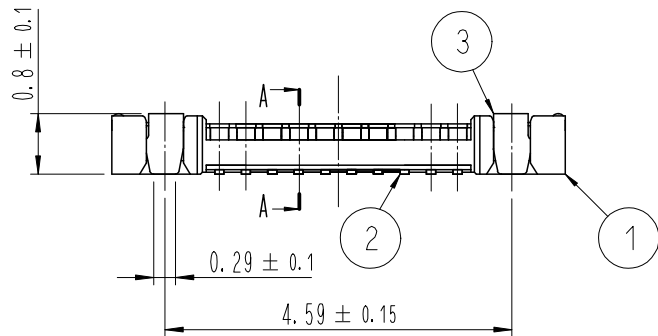
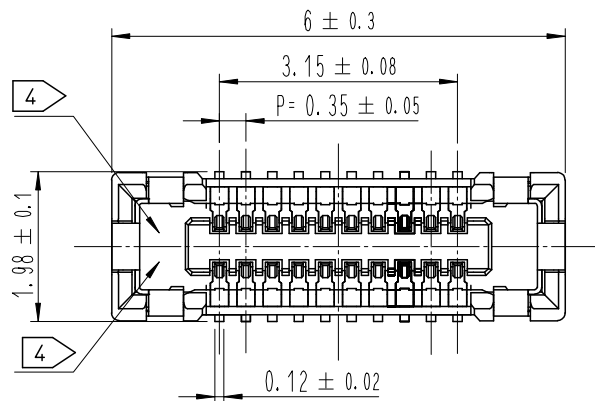


A
B
C
D
E
F

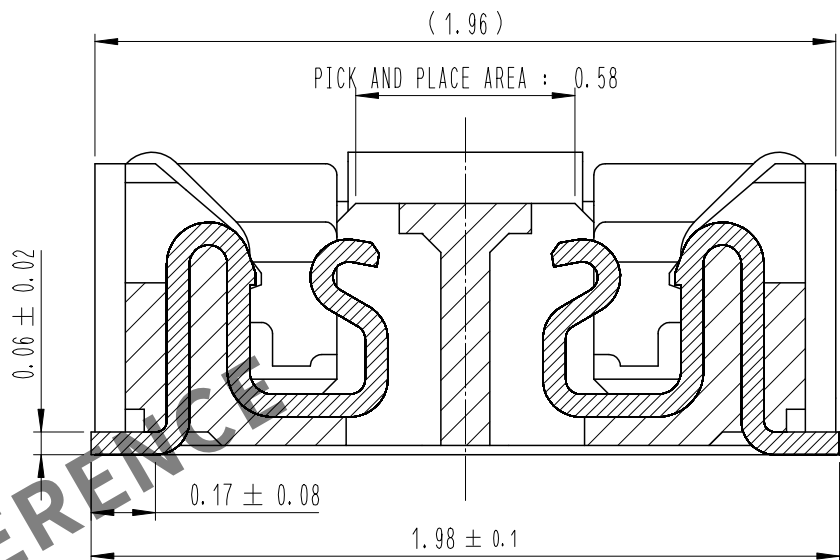


DRAWING FOR REFERENCE
This is subject to change without notice

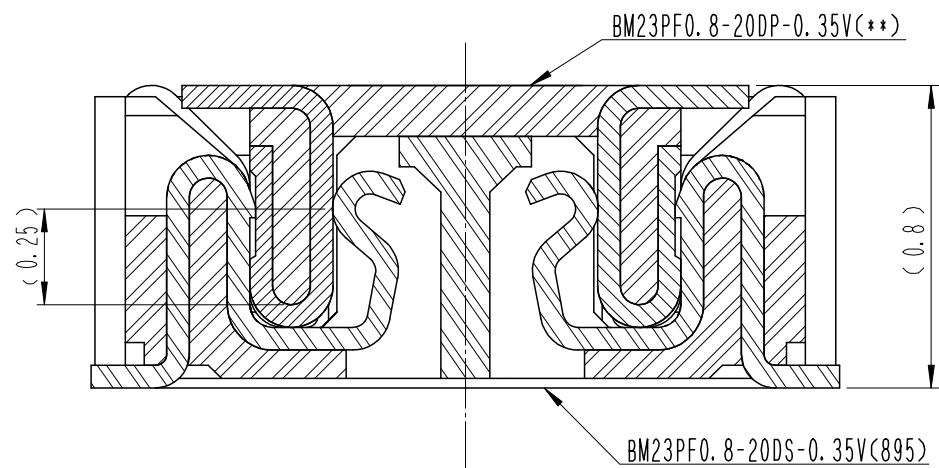
- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
 - 3. MATA FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

	△數	訂正事項	擔當	檢圖	年月日		△數	訂正事項	擔當	檢圖	年月日		
	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
△						.	△						.
△						.	△						.
△						.	△						.

A-A(50:1)



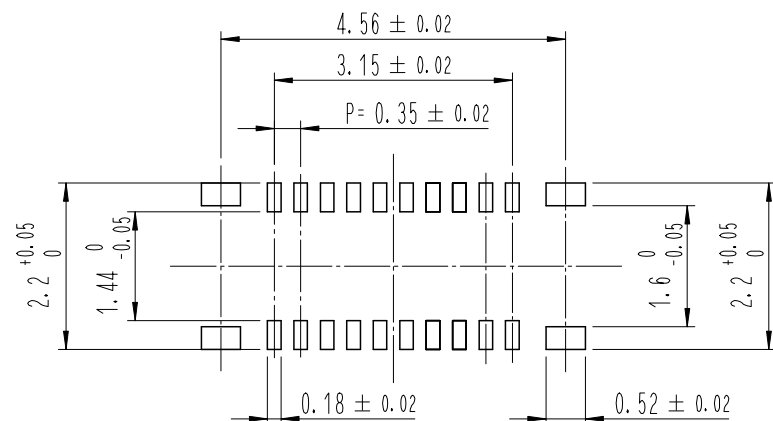
ENGAGEMENT FIGURE (50:1)



4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	COPPER ALLOY	3			
2	COPPER ALLOY	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
REMARKS			DRAWN	DESIGNED	CHECKED
			S. H. JUNG	S. H. JUNG	H. W. JO
			17. 05. 09	17. 05. 09	17. 05. 09
				APPROVED	RELEASED
				T. S. KANG	17. 05. 09
CODE NO. (OLD)	DRAWING NO. EDC3-632053		PART NO. BM23PF0.8-20DS-0.35V(895)		
	SCALE 10:1	HRS HIROSE KOREA CO., LTD.	CODE NO. CL 6644-0061-9-895		1
	UNITS mm				3

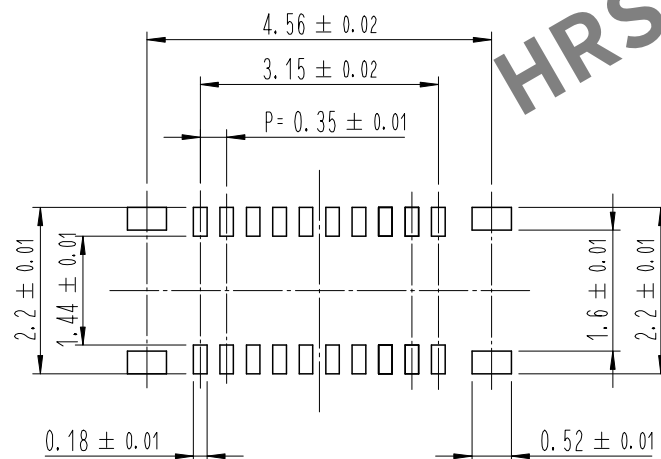
1 2 3 4 5 6 7 8

6 RECOMMENDED PCB LAYOUT

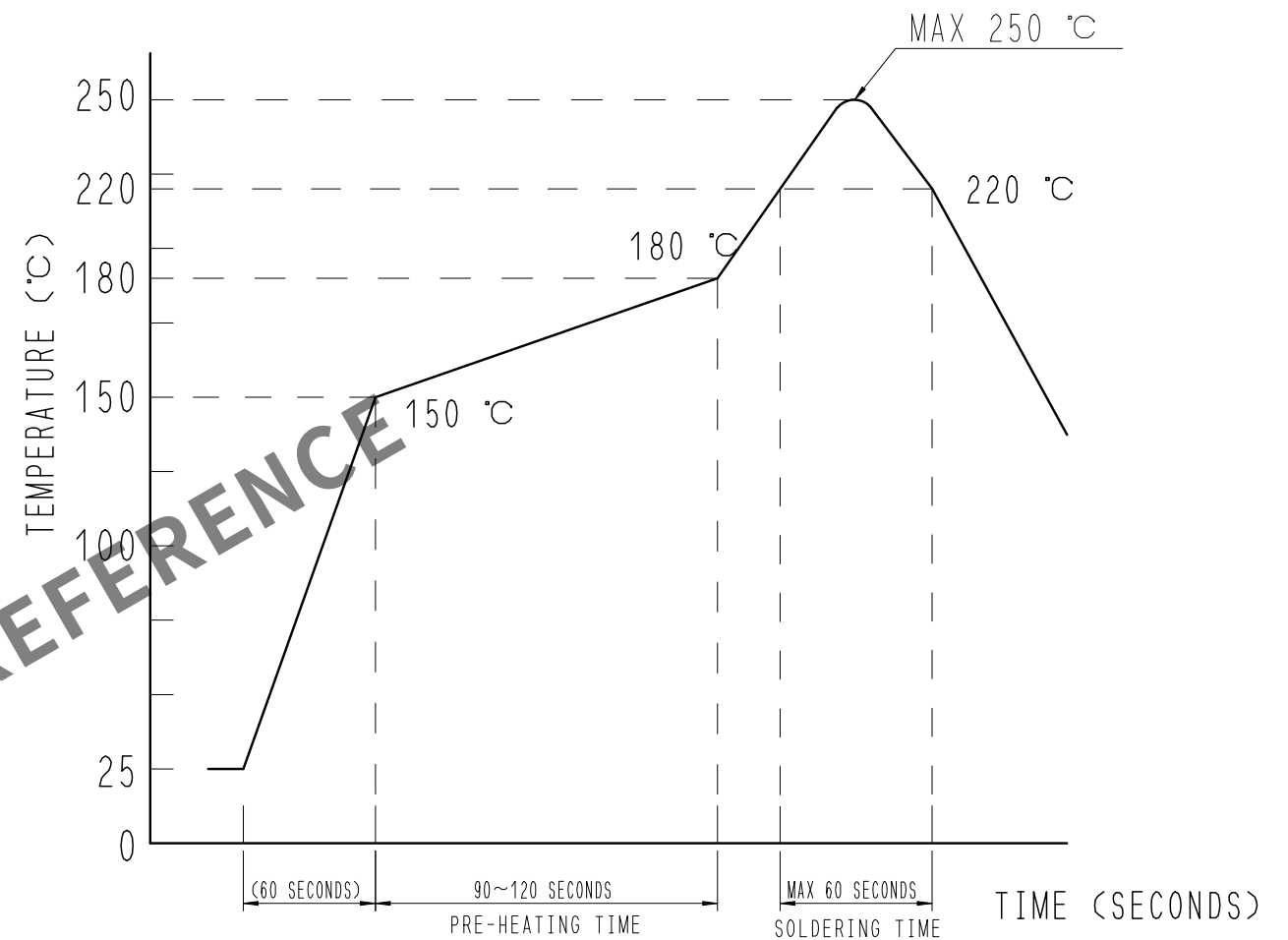


RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N2 REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220 $^{\circ}\text{C}$: 60 SEC MAX.

(PEAK TEMPERATURE: 250 $^{\circ}\text{C}$ MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE (MIN): 150 $^{\circ}\text{C}$

PRE-HEAT TEMPERATURE (MAX): 180 $^{\circ}\text{C}$

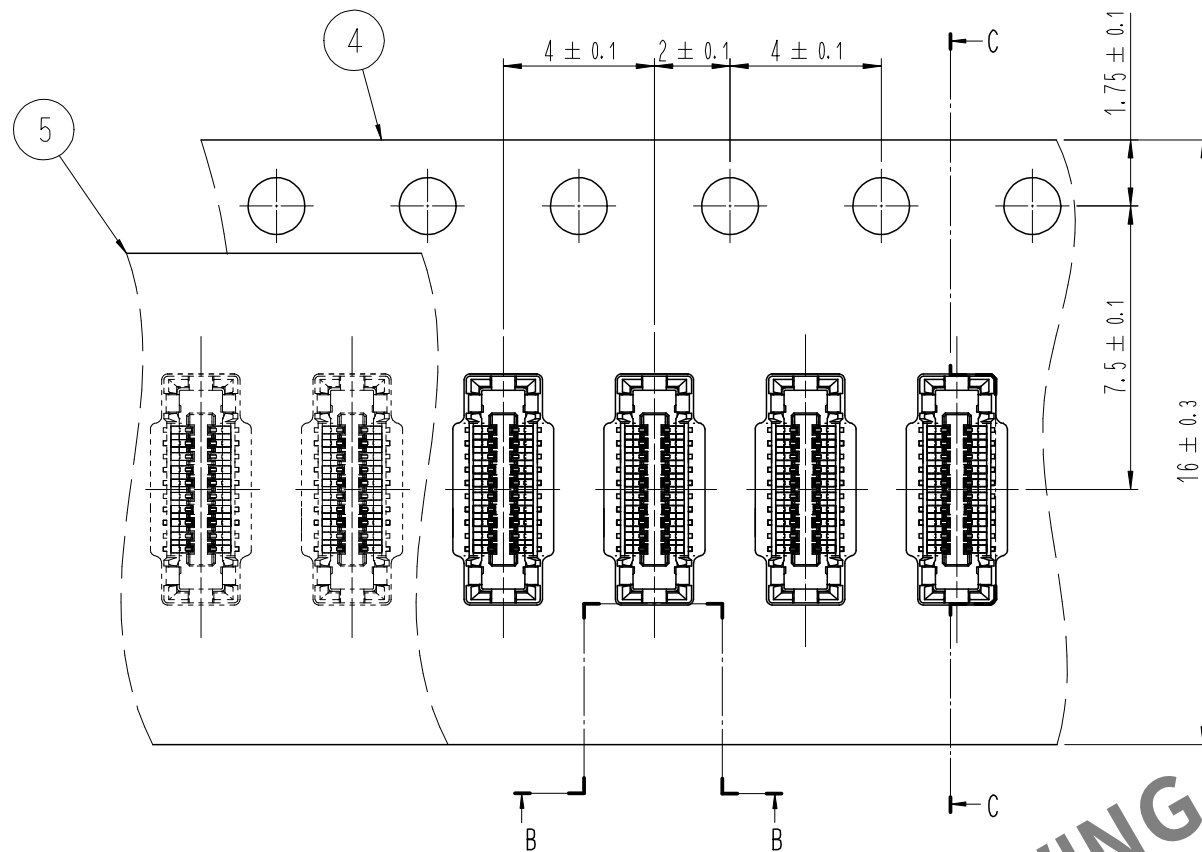
PRE-HEAT TIME: 90~120 SEC.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

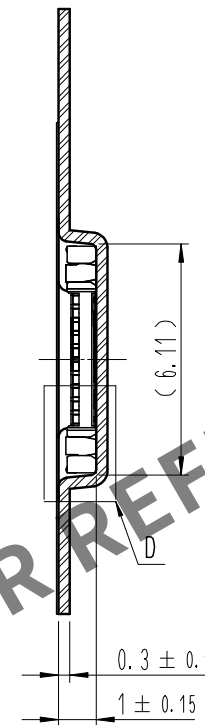
7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632053	PART NO.	BM23PF0.8-20DS-0.35V(895)
SCALE	10:1	 HIROSE KOREA CO., LTD.		
UNITS	mm			
			CODE NO	CL 6644-0061-9-895
				2/3

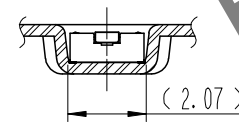
EMBOSSED CARRIER TAPE PACKAGING (5:1)



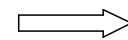
C-C (5:1)



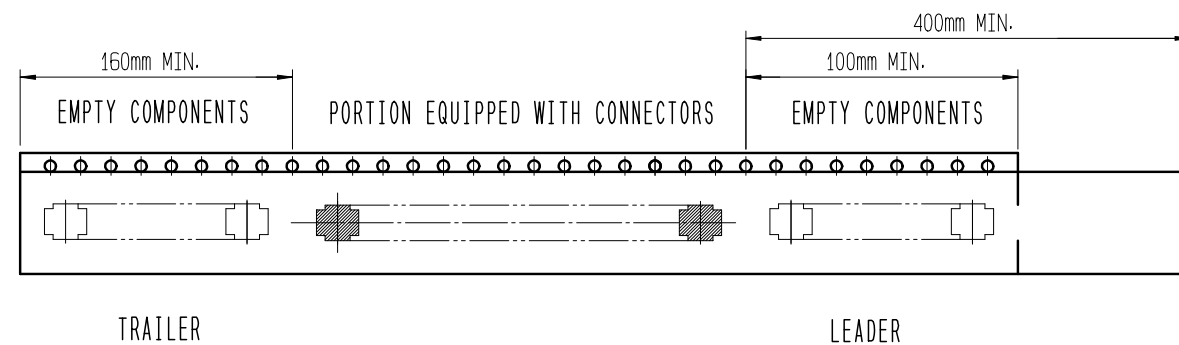
B-B (5:1)



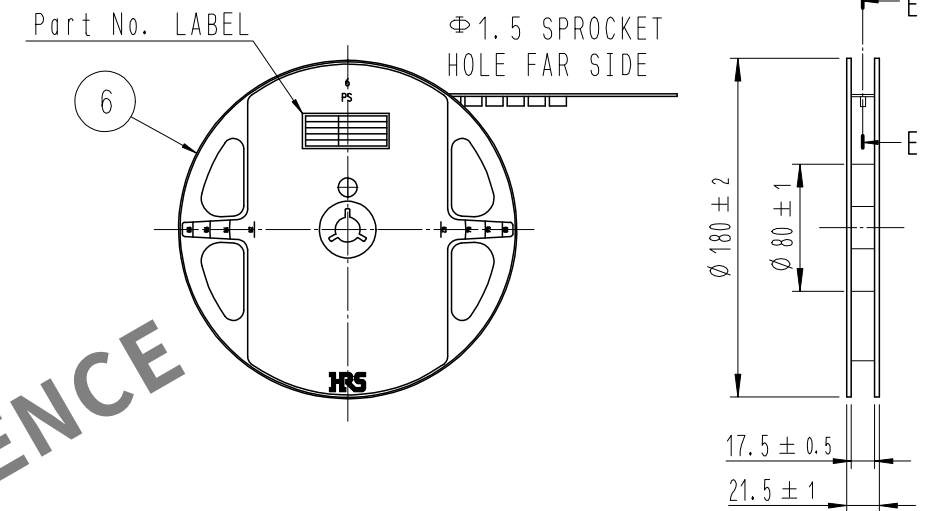
DIRECTION OF UNREELING



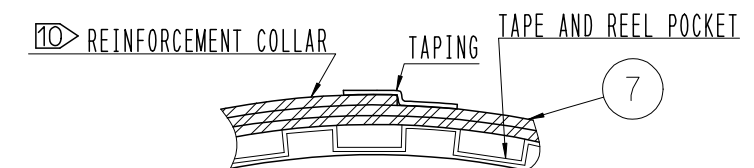
10 TAPING(FREE)



STYLE AND DIMENTION OF REEL (FREE)



E-E (FREE)



DETAIL OF PART No. LABEL

SUPPLIER	HIROSE ELECTRIC CO., LTD.
QUANTITY	1,000
PART NO.	BM23PF0.8-20DS-0.35V(895)
CODE NO.	CL 6644-0061-9-895
DATE OF MANUFACTURED	2024.03.01
生産月日	年 月 日
図番	** ** *
品名	BM23PF0.8-20DS-0.35V(895)
納入数量	1,000個
納入者	HIROSE KOREA

7 . PER REEL 1,000 CONNECTORS.

8 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

9 REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

10 AFTER PACKAGING. ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

DRAWING NO.	EDC3-632053	PART NO.	BM23PF0.8-20DS-0.35V(895)
SCALE	10:1	CODE NO.	CL 6644-0061-9-895
UNITS	mm		

HIROSE KOREA CO., LTD.

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